For assistance or to order; call (800) 531-5782

78ST300 Series

3 AMP POSITIVE STEP-DOWN INTEGRATED SWITCHING REGULATOR

Revised 6/30/98



(For dimensions and PC board layout see Package Style 600.)

Specifications

C1 = Optional 1µF ceramic C2 = Required 100µF electrolytic

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Characteristics (T _a = 25°C unless noted)	Symbols	Conditions	78ST300 SERIES			
			Min	Тур	Max	Units
Output Current	Io	Over V _{in} range	0.1*	_	3.0	А
Input Voltage Range	Vin	$I_0 = 0.1$ to 3.0A	8	-	20	V
Output Voltage Tolerance	ΔV_{o}	Over V_{in} range $T_a = 0^{\circ}C$ to $+60^{\circ}C$		±1.0	±2.0	%Vo
Line Regulation	Reg _{line}	Over V _{in} range	_	±0.4	±0.8	$%V_{o}$
Load Regulation	Regload	$0.1 \le I_o \le 3.0A$	_	±0.2	±0.4	$%V_{o}$
Ripple/Noise	Vn	V_{in} = V_{in} min, I_o = 3.0A	_	1	_	%Vo
Transient Response (with 100µF output cap)	t _{tr}	50% load change V_o over/undershoot	—	100 5.0	—	μSec %Vo
Efficiency	η	$V_{in} = 9V, I_o = 3.0A$	_	80	_	%
Switching Frequency	$f_{ m o}$	Over Vin and Io ranges	0.95	1.0	1.05	MHz
Absolute Maximum Operating Temperature Range	T _a	_	-40	-	+70	°C
Recommended Operating Temperature Range	Ta	Free Air Convection, (40-60LFM) Over V_{in} and I_o ranges	-40	_	+70**	°C
Thermal Resistance	θ_{ja}	Free Air Convection, (40-60LFM)	_	35	_	°C/W
Storage Temperature	Ts		-40	_	+125	°C
Mechanical Shock	<u> </u>	Per Mil-STD-883D, Method 2002.3	_	500	_	Gs
Mechanical Vibration	—	Per Mil-STD-883D, Method 2007.2, 20-2000 Hz, soldered in a PC board	_	10	_	G's
Weight	_	_		11	_	Grams

SUGGESTED BOARD LAYOUT COMPONENT SIDE VIE₩

* ISR will operate down to no load with reduced specifications.

** See Thermal Derating chart.

Note: The 78ST300 Series requires a 100µF electrolytic or tantalum output capacitor for proper operation in all applications.

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Series

78**5**7300

CHARACTERISTIC DATA



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